

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT7389327

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
STANLEY CHEUNG	06/14/2022
GEZA KURCZVEIL	06/14/2022
YUAN YUAN	06/14/2022
XIAN XIAO	06/14/2022
RAYMOND G. BEAUSOLEIL	06/14/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HEWLETT PACKARD ENTERPRISE DEVELOPMENT LP
<b>Street Address:</b>	11445 COMPAQ CENTER DRIVE WEST
<b>City:</b>	HOUSTON
<b>State/Country:</b>	TEXAS
<b>Postal Code:</b>	77070
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17843352
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(970)778-4063
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	4046480513
<b>Email:</b>	hpe.ip.mail@hpe.com
<b>Correspondent Name:</b>	HEWLETT PACKARD ENTERPRISE
<b>Address Line 1:</b>	3404 E. HARMONY ROAD
<b>Address Line 2:</b>	MAIL STOP 79
<b>Address Line 4:</b>	FORT COLLINS, COLORADO 80528
<b>ATTORNEY DOCKET NUMBER:</b>	P168898US
<b>NAME OF SUBMITTER:</b>	SARA VAUGHAN
<b>SIGNATURE:</b>	/Sara Vaughan/
<b>DATE SIGNED:</b>	06/17/2022
<b>Total Attachments: 2</b>	

source=P168898US\_Assignment\_61CT-352431#page1.tif

source=P168898US\_Assignment\_61CT-352431#page2.tif

**PATENT**

**REEL: 060239 FRAME: 0039**

**COMBINED DECLARATION AND ASSIGNMENT  
FOR UTILITY AND DESIGN PATENT APPLICATION****Title of  
Application**

PARITY TIME SYMMETRIC DIRECTIONAL COUPLERS WITH PHASE TUNING

**Filing Date:** June 17, 2022**Application No.:** 17/843,352**DECLARATION**

As a below named inventor, I hereby declare that:

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**ASSIGNMENT**

In this Assignment, the "Patent Items" include the above-identified application for Patent and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Patent, and any and all other Patent(s) of any countries thereto which may be granted thereon or therefore, and any reissues, or reexaminations, or extensions of said Patent(s).

I/We, the undersigned (each):

hereby confirm the assignment and transfer of the entire right, title and interest, including the right of priority, in, to and under the Patent Items to Hewlett Packard Enterprise Development LP, a Texas Limited Partnership having its principal place of business in Houston, Texas, (hereinafter HPED) by virtue of a previously executed agreement,

acknowledge that I/we have previously agreed to assign and transfer to HPED the entire right, title and interest, including the right of priority, in, to and under the Patent Items, and

to the extent not already effected by a previously executed agreement, for good and valuable consideration, the receipt of which is hereby acknowledged, and in furtherance of my/our obligations to HPED, and to its subsidiaries and affiliates, hereby assign and transfer to HPED, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under the Patent Items.

I/we additionally authorize HPED to file applications in my/our name for Patent in any country, to be held and enjoyed by HPED, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said Patent Items, to HPED, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to HPED, or to its nominee, all known facts respecting said invention(s) or improvement(s), said Patent Items, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid HPED, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by HPED;

AND I/we hereby authorize and request the official of any country or countries whose duty it is to issue patents on applications as aforesaid, to issue to HPED, as assignee of the entire right, title and interest, any and all Patent(s) for said invention(s) or improvement(s) which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

Record ID: P168898US

I/we further authorize and direct the attorneys of record to insert the filing date and application number of said application for Patent, now identified by the Record ID and title set forth above, as soon as the same shall have been made known to them.

IN WITNESS WHEREOF, I/we hereunto set my/our hand(s) and seal(s):

<u>1</u> <u>Stanley Cheung</u> <u>1</u>	<u>6/14/2022</u>
Inventor's Signature	Date
Stanley Cheung	
First/Middle Name/Last Name	
<u>1</u> <u>geza kurczveil</u> <u>1</u>	<u>6/14/2022</u>
Inventor's Signature	Date
Geza Kurczveil	
First/Middle Name/Last Name	
<u>1</u> <u>Guan Guan</u> <u>1</u>	<u>6/14/2022</u>
Inventor's Signature	Date
Yuan Yuan	
First/Middle Name/Last Name	
<u>1</u> <u>Xian Xiao</u> <u>1</u>	<u>06/14/2022</u>
Inventor's Signature	Date
Xian Xiao	
First/Middle Name/Last Name	
<u>1</u> <u>Raymond G. Beausoleil</u> <u>1</u>	<u>06/14/2022</u>
Inventor's Signature	Date
Raymond G. Beausoleil	
First/Middle Name/Last Name	